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<table border="1"> <caption>Data points estimated from the graph</caption> <thead> <tr> <th>Pyrrole/Salt Molar Ratio</th> <th>Conductivity (S/cm⁻¹) - AgNO₃</th> <th>Conductivity (S/cm⁻¹) - AgTS</th> </tr> </thead> <tbody> <tr><td>10⁰</td><td>10^{-1.5}</td><td>10^{-1.5}</td></tr> <tr><td>10^{0.5}</td><td>10^{-1.2}</td><td>10^{-1.2}</td></tr> <tr><td>10¹</td><td>10⁻¹</td><td>10^{-1.5}</td></tr> <tr><td>10^{1.5}</td><td>10^{-1.5}</td><td>10^{-2.5}</td></tr> <tr><td>10²</td><td>10⁻⁵</td><td>10⁻⁶</td></tr> </tbody> </table>				Pyrrole/Salt Molar Ratio	Conductivity (S/cm ⁻¹) - AgNO ₃	Conductivity (S/cm ⁻¹) - AgTS	10 ⁰	10 ^{-1.5}	10 ^{-1.5}	10 ^{0.5}	10 ^{-1.2}	10 ^{-1.2}	10 ¹	10 ⁻¹	10 ^{-1.5}	10 ^{1.5}	10 ^{-1.5}	10 ^{-2.5}	10 ²	10 ⁻⁵	10 ⁻⁶
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(57) Abstract																					
<p>The present invention provides electronically conducting polymer films formed from photosensitive formulations of pyrrole and an electron acceptor that have been selectively exposed to UV light, laser light, or electron beams. The formulations may include photoinitiators, flexibilizers, solvents and the like. These formulations can be used to manufacture multichip modules on typical multichip module substrates, such as alumina, fiberglass epoxy, silicon and polyimide. The formulations and methods of the invention enable the formation of passive electronic circuit elements such as resistors, capacitors and inductors in multichip modules or printed wiring boards.</p>																					

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**METHOD OF MANUFACTURING PASSIVE ELEMENTS
USING CONDUCTIVE POLYPYRROLE FORMULATIONS**

This invention was made with government support under contract F29601-94-C-0097 awarded by the Air Force. The government has certain rights in this invention. This application is a continuation-in-part of U.S. Patent Application Serial No. 08/491,625 filed on June 19, 1995 and U.S. Patent Application Serial No. 08/492,235, filed on June 19, 1995.

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FIELD OF THE INVENTION

The present invention relates to conductive polymers and their use in electronic applications. More particularly, the present invention relates to photosensitive solutions of 10 pyrrole and direct metallization processes for preparing electronic circuits on non-conducting substrates. Even more particularly, the present invention relates to preparation of passive electronic circuit elements such as resistor networks, inductors, and capacitors suitable for implementation into printed wiring boards (PWBs) and multichip modules (MCMs) through multilayer photopolymerization of conducting polymer films.

15

BACKGROUND OF THE DISCLOSURE

Printed wiring boards (PWBs) consist of non-conducting substrates, such as 20 fiberglass/epoxy or polyimide, on which conducting circuits are deposited and discrete passive elements may be mounted. Multichip modules (MCMs) are devices that consist of a collection of integrated circuit (IC) chips or die that are mounted on a high-density interconnect substrate, such as alumina, with a high utilization ratio of die area to substrate area (up to 90-95%). The advantages of MCM technology over conventional packaging schemes, such as printed wiring boards, include very high packaging densities, clock speeds 25 in excess of 500 MHz, lower power due to reduced capacitance, higher reliability, and better thermal matching of the die to the substrate material. The current disadvantages include the

high cost of substrates, limited availability of bare die, and difficulties in testing at high clock speeds.

An important requirement for virtually every PWB and MCM application today is extremely high reliability. A demanding series of accelerated life tests, including moisture resistance, salt atmosphere, thermal shock, thermal cycle, constant temperature bake, lead integrity, and fine and gross leak tests, are usually performed on assembled PWBs and MCMs. Since semiconductor die are the major building blocks of an MCM, the first focus of yield, testability, and diagnostic evaluation must be at the die level (KGC concept of a "known good die"). However, performance analysis must be done for each product level (die, MCM, and system) and for each test condition.

A substantial number of different approaches are used by various vendors in the field. For example, MCMs are often classified according to the substrate technology (e.g. MCM-L, -C, and -D) which determines the possible interconnect density. The complexity of MCM design is reflected in the accepted definitions of the types of modules being offered to electronics manufacturers.

The use of a wide variety of processes has resulted in a lack of standardization which complicates the selection of substrates, choice of interconnection, and passive element integration technology. Thus, passive components (e.g., resistors, capacitors, inductors) are often attached discretely to the previous level of assembly. The insertion of low-profile passive components into PWBs and MCMs is costly, laborious and time consuming. Processes compatible with existing technologies which are able to incorporate the fabrication of passive elements into existing technologies are needed.

In hybrid and MCM technologies, passive components are produced by thin films (<5 μ m), thick films (>10 μ m) or may be discretely attached to the substrate, e.g. chip-resistors and chip-capacitors. Discrete passive components are less desirable because of laborious insertion of the components into the MCM circuit, and their use is limited to special conditions where very low or high values are needed.

Thin film technology is based on the deposition of passive elements by electron-beam evaporation or sputtering. Thin film resistors may be nickel-chromium, tantalum nitride, or

silicon carbide films; and dielectrics include silicon monoxide, silicon dioxide, and tantalum oxide. In thick film technology, inks or pastes are screen printed to the ceramic substrate. The resistive components of resistor pastes may comprise: ruthenium oxide, thallium oxide, indium oxide, mixtures of precious metals or tungsten-tungsten carbide. Dielectric materials 5 are largely based on the ferroelectric ceramic barium titanate with various additives and glass-ceramic mixtures.

Electronically conducting polymers have often been categorized as non-processable and difficult to manage or manipulate, because of their insolubility in the conducting form. Only recently has it been shown that polymers such as polyaniline can be dissolved using 10 functionalized sulfonic acids. For polypyrrole, this can be achieved by using its derivatives [e.g., poly (3-octylpyrrole)] which are known to be soluble in different solvents, or by treatment in dilute aqueous sodium hypochlorite solutions, ammonia or mono-, di- or tri-substituted amine (co)solvents. Another method of solubilizing polypyrrole is the process of polypyrrole chain deprotonation in basic solutions, which causes a transformation of 15 conducting polypyrrole into a non-conducting polymer of quinoid structure.

The lack of processability of conducting polymer materials, e.g., solution or melt processing, infusability and poor mechanical properties, e.g., ductility, have slowed down their emerging commercial applications. While electrochemical preparation of conducting polymers has been shown to be the most satisfactory process from the viewpoint of 20 fundamental investigations, it is likely to be inappropriate for the large-scale industrial production of bulk quantities of these materials. This is particularly true where large molecular entities, e.g., copolymers or different additives, need to be incorporated into conducting polymer matrices in order to obtain tailored performance characteristics.

Consequently, there remains a need for improved methods of manufacturing passive 25 electronic elements in both printed wiring boards and multichip modules. It would be desirable to have a conducting polymer that avoids polymer solubility problems, can easily incorporate additives to obtain desirable characteristics such as flexibility and photoinitiation, minimizes hazardous chemicals, requires fewer process steps to apply/deposit/coat a workpiece, facilitates increased conductor densities on a substrate

surface, and allows for passive electronic elements to be formed directly on the substrate. Furthermore, it would be desirable to have a method of manufacturing printed wiring boards and multichip modules having increased interconnect densities, improved manufacturability and improved product quality.

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SUMMARY OF THE INVENTION

10 The preferred embodiments of the present invention provide methods of forming an electronically conducting polymer resistor on a conducting or nonconducting substrate surface. Resistors are formed by applying a thin film of a formulation comprising pyrrole monomer and a salt onto the substrate surface. The salt consists of an electron acceptor containing Ag^+ cations and a dopant anion selected from the group consisting of NO_3^- , NO_2^- , BF_4^- , ClO_4^- and tosylate. A portion of the film is then photopolymerized to form a resistor by exposure to ultraviolet light, laser light or an electron beam, while the unpolymerized portion of the film is removed from the substrate with a solvent. The pyrrole:salt molar ratio in the formulation is greater than about 0.5, and the resistor has an electrical resistance substantially determined by the molar concentration of the salt in the formulation.

15 20 25 The preferred embodiment of the present invention also provides a method of forming a plurality of electronically conducting polymer resistors having different electrical resistances on a common substrate surface. The method involves preparing a plurality of formulations comprising a monomer and a salt, wherein the salt consists of an electron acceptor consisting of Ag^+ cations and a dopant anion selected from the group consisting of NO_3^- , NO_2^- , BF_4^- , ClO_4^- and tosylate, and wherein each of the formulations has a different molar concentration of salt for forming resistors having resistances within a given range. A thin film of a formulation is then applied onto the substrate surface before photopolymerizing a portion of the film to form a resistor. The photopolymerized portion extends between two contact points and has sufficient thickness and width so that the overall electrical resistance

between the two contact points is somewhat less than a resistance specific. The unpolymerized portion of the film is removed from the substrate with steps are repeated for each of the plurality of formulations. Heat may resistor to provide a thermal cure.

5 The methods may also include the steps of measuring the over resistor and increasing the overall resistance of the resistor up to a specific trimming the resistor with a laser. These steps may be repeated until each overall resistance near the resistance specified for that resistor.

10 The preferred embodiment of the present invention further provides forming an electronically conducting polymer inductor on a nonconducting substrate. After preparing and applying a formulation, as set out above, a plurality of lines are photopolymerized in the film. The unpolymerized portion of the film is removed from the substrate with a solvent and a layer of dielectric material is deposited on the horizontal lines to form a top surface of the structure. Holes are drilled down through the layer of dielectric material and into each end of each lower horizontal line. 15 applying a thin film of the formulation to the holes and top surface of the dielectric material. The film is selectively photopolymerized to form vertical vias and upper horizontal lines, wherein the ends of each upper horizontal line connect with the vertical vias. The upper horizontal lines, lower horizontal lines and vertical vias are all 20 conducting and cooperate to form a coil-like pathway.

The preferred embodiment of the present invention also provides forming a solid state electrolytic capacitor in which a conducting polymer is deposited on a dielectric layer. A thin film of a formulation is deposited on a dielectric layer. The film is photopolymerized and the unpolymerized portion of the film is removed from the substrate. A layer of palladium is then deposited onto the surface of the polymer by immersion in solution consisting of a palladium containing salt. The electrodeposition of a metal conductor layer such as gold, copper or palladium layer.

The preferred embodiment of the present invention encompasses a method

a plurality of passive elements on a common substrate surface. This method includes the steps of preparing a formulation, as set out above, forming an electronically conducting polymer resistor on a conducting or nonconducting substrate surface, forming a solid state electrolytic capacitor in which a conducting polymer is applied as an electrolyte, and forming 5 an electronically conducting polymer inductor on a nonconducting substrate surface.

BRIEF DESCRIPTION OF THE DRAWINGS

10 Figure 1 is a graph illustrating the dependence of conductivity on the type and concentration of dopant anions present in photopolymerizable polypyrrole-based formulations;

Figure 2 is a graph illustrating the dependence of electrical resistance of photopolymerized polypyrrole films on the electron acceptor:monomer mole ratio in the starting formulation;

15 Figure 3 is a graph illustrating the dependence of curing time on the concentration of photoinitiator;

Figure 4 is a graph illustrating the dependence of conductivity on photoinitiator concentration;

20 Figure 5 is a graph illustrating the dependence of curing time on the amount of dodecyl sulfate used as flexibilizer;

Figure 6 is a graph illustrating the dependence of curing time and conductivity on the amount of dodecyl sulfate used as flexibilizer;

Figure 7 is a graph illustrating the dependence of resistivity of photopolymerized polypyrrole films on the ratios of pyrrole:aniline monomers;

25 Figure 8 is a photograph of alumina substrates with laser and electron beam patterned lines of electronically conducting polypyrrole;

Figure 9 contains scanning electron micrographs of the cross-sections of polypyrrole films formed electrochemically and photochemically;

Figure 10 contains scanning electron micrographs of the surfaces of polypyrrole films

formed electrochemically and photochemically;

Figure 11 is a flow chart comparing the steps of conventional PWB fabrication with those of the present invention;

5 Figure 12 is a photograph of black conducting polypyrrole lines on a fiberglass/epoxy PWB substrate patterned using UV illumination through a shadow mask, wherein one line has been electrodeposited with copper;

Figure 13 is a photograph of a copper-on-polypyrrole plated 0.025 inch diameter through-hole; and

10 Figure 14 is a perspective view of an inductor fabricated with photopolymerized conducting polymers in vertical paths through a dielectric layer;

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENT

One embodiment of the present invention provides a novel photopolymerization 15 process for the preparation of high-quality, passive electronic elements using electronically conducting organic polymer films. The process utilizes a simple formulation that consists of a pure monomer (such as pyrrole or aniline), a salt and a solvent. Polymerization is induced by light allowing thin polymer patterns to be photopolymerized on typical PWB substrates, such as fiberglass/epoxy or polyimide, and MCM substrates, such as alumina 20 (Al_2O_3), berillia (BeO), fiberglass/epoxy, silicon, polyimide and ceramic-filled polytetrafluoroethylene.

Direct writing of patterns can be performed with an argon laser or by electron beam irradiation for improved resolution. When photopolymerizing electronically conducting polymer dry-film photoresists, a contact mask having a desired pattern inscribed therein can 25 be placed over the substrate to block out light from undesired areas. The mask/board assembly is then exposed to UV (or electron beam) irradiation, promoting photopolymerization of the cast formulation (or dry film) in regions where light passes through the pattern inscribed in the mask. The photopolymerizable thin film formulation not exposed to the radiation can then be removed by means of an appropriate solvent.

The formulations of the preferred embodiments of the present invention include a salt that serves both as an electron acceptor for oxidation of the monomer(s) and as a dopant to preserve electroneutrality in the oxidized polymer. Preferred electron acceptors undergo very slow oxidation of the monomer in the dark (1-2 days) and have the highest conductivities.

5

Polypyrrole (PPY) can be chemically prepared using inorganic (Fe^{3+} and Cu^{2+} ions) or organic (chloranil) electron acceptors. When inorganic acceptors are added to pyrrole-containing solutions a powdery polymer material results almost immediately after the addition. Therefore, cations having too high an oxidation potential are not suitable for photopolymerization of polypyrrole. Several attempts were made to use organic electron acceptors, but photopolymerization of black conductive PPY films was unsuccessful. It has been shown that electron acceptors with proper oxidation potential (e.g. Ag^+ , Fe^{3+} or Cu^{2+} ions) and dopant (e.g. NO_3^- , BF_4^- ; tosylate, etc.) play a decisive role in determining the conductivity of the conducting polymer film. The preferred electron acceptors are the silver salts (such as $AgNO_3$, $AgClO_4$ and $AgNO_2$), with the most preferred being silver nitrate, $AgNO_3$.

The conductivity (or resistivity) of a polymer film can be modified by changing the molar ratio of monomer to electron acceptor over a wide range. Figure 2 shows the resistance of conducting polymer films at various ratios of monomer to electron acceptor above about 0.5. Monomer/electron acceptor ratios ranging between about 2 and about 100 are preferred for producing electronically conductive polymer films. The electrical conductivity of the polymers decreases (resistance increases) with decreasing concentration of electron acceptor (increasing monomer to electron acceptor ratio). High electron acceptor concentrations, such as monomer/electron acceptor molar ratios below about one, have been found to produce films that are thicker than desirable.

A polymer network can be formed by promoting the polymerization of a monomer, oligomer, or mixtures of monomers and/or oligomers. Polymerization is a chain reaction that can develop very rapidly, especially when intense UV radiation is used to produce the initiating species. This UV-curing reaction leads ultimately to a three-dimensional polymer

network. Since most of the monomers or oligomers commonly employed do not produce initiating species with a sufficiently high yield upon UV exposure, it is preferred to introduce a photoinitiator that will allow the polymerization to start. A typical UV-curable formulation, therefore, will contain two basic components: (i) a photoinitiator, and (ii) a monomer, oligomer, or a mixture of monomers and/or oligomers.

The choice of the photoinitiator is of prime importance in light-induced polymerizations, since it directly governs the cure rate. A suitable photoinitiator system must possess high absorption in the emission range of the light source. The photoinitiator must also form an excited state having a short lifetime to avoid quenching by oxygen or the monomer and split into reactive radicals or ionic species with the highest possible quantum yield. Other factors to be considered in selecting the proper photoinitiator include solubility in the monomer, storage stability and the nature of the photo-products, which should not be colored, toxic or induce some degradation of the polymer upon aging. Photoinitiators can be classified into three major categories, depending on the kind of mechanism involved in their photolysis: (i) radical formation by photo-cleavage; (ii) radical generation by hydrogen abstraction, and (iii) cationic photoinitiators.

Cationic photoinitiators have proven to be particularly useful in the photopolymerization of polypyrrole from pyrrole monomers in solution. Besides their specificity, cationic-initiated photopolymerizations have the advantage of being insensitive to atmospheric oxygen. In the absence of nucleophilic reagents, the chain reaction will thus continue to develop after the illumination has ceased and provide a beneficial post-cure effect that can be enhanced by thermal treatment. The preferred post-photopolymerization thermal treatment involves heating the polymer at temperatures between about 80 and about 120 degrees Celsius for about three hours, with the most preferred temperature being about 100 degrees Celsius.

Thermally stable photoinitiators for cationic polymerizations of commercial significance include the onium salts, such as triarylsulfonium and diaryliodonium, with complex metal halide anions. A key feature of these photoinitiators is the low nucleophilicity of the anions which reduces termination processes and allows ambient

temperature cationic polymerization to proceed. The absence of air inhibition represents a distinguishing feature of cationic, as compared to radical, polymerization.

The photoinitiators investigated include a titanocene radical photoinitiator (such as IRGACURE™ 784 available from Ciba Geigy, located in Ardsley, New York), a cationic ferrocinium photoinitiator (such as a (h₆-benzene)(h₅-cyclopentadienyl)iron(II)-hexafluorophosphate available as IRGACURE™ 261 from Ciba Geigy, located in Ardsley, New York), triaryl sulphonium PF₆⁻ salts (such as CYRACURE™ 6990, available from Union Carbide, located in Danbury, Connecticut), triaryl sulphonium SbF₆⁻ salts (such as CYRACURE™ 6974, available from Union Carbide, located in Danbury, Connecticut).

10 The photoinitiators are preferably added to the monomer in amounts less than about 8 weight percent, with the most preferred amounts being between about 0.2 to about 0.8 weight percent.

Photopolymerization of pyrrole alone, or pyrrole mixed with a photoinitiator such as titanocene, yields a transparent yellow film exhibiting insulating properties. Resistances of 15 over 20 MΩ are measured by an ohmmeter. When AgNO₃, an electron acceptor, is dissolved into the pyrrole prior to curing, a black polymer film characteristic of conducting polypyrrole is formed.

In general, both electropolymerized and photopolymerized polypyrrole films suffer 20 from poor mechanical properties. They lack flexibility, either as stand alone films or as coatings. Three approaches have been found to improve the mechanical properties of photopolymerized polypyrrole: (i) incorporating large amphophilic (surfactant) organic anions into the polypyrrole structure, (ii) photo-copolymerizing a suitable comonomer material with pyrrole, and (iii) including commercial flexibilizers. The preferred surfactants are large anionic surfactants, such as the sodium salts of dodecyl sulfate (DDS) and 25 dodecylbenzene sulfonate (DDBS). The preferred comonomer is aniline. The preferred flexibilizer is polyethylene glycol diglycidyl ether.

In accordance with preferred embodiments of the present invention, formulations can include a mixture of monomers which can be photopolymerized to form copolymers. While photo-copolymerizations can be achieved with many monomer pairings, the preferred

monomer pairs for the lithographic production of an electronically conducting copolymer on a non-conducting substrate are comprised of: (i) pyrrole in combination with: (ii) a sub-stoichiometric amount of silver nitrate (such as a molar ratio of pyrrole to silver nitrate of about 8:1) and with (iii) fifteen mole percent aniline relative to pyrrole. The mixed 5 monomer formulation is then diluted with an equivalent volume of acetonitrile to provide good contact with the substrate.

The components of photopolymerizable solutions may be mixed in a glass vial that excludes the penetration of light. The solutions may be sonicated to facilitate dissolution and 10 homogenization of the formulation. Since a slow chemical polymerization of pyrrole takes place over a period of one to two days in the presence of Ag^+ ions, it is preferred that fresh photopolymerizable formulations be prepared immediately prior to polymerization.

A thin layer of the formulation is then cast and evenly spread on the surface of a selected substrate typically having a surface area of between about 1 and about 4 square 15 centimeters (cm^2). The preferred methods of spreading the formulation over the substrate to achieve a thin layer having uniform thickness include brush coating, spraying, dipping and spin coating, with the most preferred method being spin coating.

After casting of the photopolymerizable solution onto a substrate and formation of an air-dried nonconducting film, the oxidation process is initiated by irradiation. The preferred 20 irradiation methods are those which selectively expose only discrete regions or lines on the coated substrate, such as exposure by ultraviolet light through a contact mask, direct laser imaging, or electron beam imaging. Using these methods, thin polymer patterns (lines and through-holes) are readily polymerized on various conducting and nonconducting substrates. Multiple coating-curing cycles (providing up to 10 layers) can be carried out in order to 25 produce thick uniform films.

Photopolymerizations according to the preferred embodiments of the present invention can be accomplished with a 200-Watt mercury-xenon lamp focused through a lens vertically downward onto a circular area of less than one centimeter in diameter. All the optical accessories should be made of fused silica in order to allow high energy UV as well

as visible light to pass therethrough.

Preferred embodiments of the present invention use the radiation as the driving force to induce electron transfer from the monomer species in a cast solution film to the electron acceptor, also present in the formulation. As the concentration of oxidized monomer increases, coupling between the oxidized monomer units begins. This process continues, resulting in growth of the conducting polymer chains. Since the polymer is oxidized, the anion present in the formulation intercalates into the polymer, maintaining electroneutrality.

The photopolymerization process does not require a conducting substrate for deposition to take place, and conducting polymer films and/or lines of various thickness, typically between about 5 and about 300 microns can be readily photopolymerized on typical PWB substrates (e.g., fiberglass/epoxy, polyimide) and MCM (e.g., alumina) as well as on metals, ceramic, silicon, GaAs, glass, paper, Teflon, Mylar and polystyrene substrates. The processes of the preferred embodiments of the present invention are much simpler than techniques known in the art and offer a high potential and flexibility for adaptation to a variety of PWB technologies.

The photopolymerization process of the preferred embodiments of the invention include the following steps:

- (i) a photopolymerizable formulation is applied on a substrate;
- (ii) after air-drying, a dry negative prepolymer film is exposed to laser light, an electron beam or to a UV lamp through a shadow mask;
- (iii) the illumination induces photopolymerization of the prepolymer film at exposed areas rendering the exposed areas insoluble; and
- (iv) the non-polymerized (non-illuminated) areas are washed off with an environmentally safe solvent (acetone) or water, leaving a pattern of conducting polymer lines.

The main advantage of the photopolymerization process, compared to electrochemical and/or chemical polymerizations, is that it allows properties of conducting polymer films to be easily designed and optimized by incorporating molecular species into the polymer structure. For example, it is possible to change the conductivity of the polymer

by controlling the amount of the electron acceptor and dopant anions present in the formulations. The same oxidatively coupled cationic polymer is formed through photopolymerization as through electrochemical polymerization, except that the anion/monomer ratio is much higher (1 : 1.3) compared to that found in electrochemically formed films (1 : 4). This is a desirable feature because with more anions in the polymer matrix, more charge can be introduced onto the polymer chains and, consequently, higher conductivities may be achieved.

EXAMPLE 1

10

A separate investigation involving both photopolymerization and thermal polymerization processes was performed on samples having two different electron acceptor salts, AgNO_3 and AgTs , at rather low concentrations (pyrrole:electron acceptor = 50:1). Four samples were cured at the same time either thermally or by photopolymerization. Curing times were determined by observing the solidification of the surface and by applying a simple pencil hardness test, often used in the polymer coating industry for semiquantitative determination of curing quality. The results are summarized in Table 1.

Thermally cured polymer films, either with AgNO_3 or AgTs as an electron acceptor, were of very poor quality, rough and lacked a uniform color, indicating nonhomogeneous polypyrrrole films. Thermal curing of the first layer proceeded with incomplete coverage of the exposed substrate surface and curing resembled that of simple drying of the solution. On the other hand, photopolymerization of the first layer resulted in a completely covered substrate surface. When more layers were added, curing times became longer, because of the penetration of freshly added formulation into the existing layers. Curing times for films where silver tosylate was added as the electron acceptor salt were longer than for AgNO_3 -containing samples. This was expected, because diffusion of larger (organic) anions into polymer films being formed (in order to satisfy the neutrality of an oxidized polymer) is much slower than for smaller anions, like nitrates. Thermal curing required curing times 2 - 3 times longer than the process of photopolymerization. This is evident especially where

tosylates are used as electron acceptors.

5 TABLE 1. Comparison of photopolymerized and thermally polymerized polypyrrole
10 films (pyrrole/electron acceptor molar ratio was 50:1; Photoinitiator: 3 wt% IRGACURE™
15 261)

LAYER NUMBER	ELECTRON ACCEPTOR	AgNO ₃		AgTs	
		PHOTO-POLYMERIZED	THERMALLY POLYMERIZED	PHOTO-POLYMERIZED	THERMALLY POLYMERIZED
FIRST LAYER	CURE TEMPERATURE °C	68	69	68	69
	CURING TIME min	2	3.5	3	18
	POLYMER FILM APPEARANCE	smooth, black, brittle	incomplete coverage, gray-black, rough, brittle	smooth, green-black, brittle	incomplete coverage, gray-green black, rough, brittle
FIFTH LAYER	CONDUCTIVITY S cm ⁻¹	9.7×10^{-3}	3.8×10^{-2}	4.1×10^{-4}	6.0×10^{-5}
	CURE TEMPERATURE °C	68	68	67	68
	CURING TIME min	7	8	9	20
	POLYMER FILM APPEARANCE	smooth, black, brittle	gray-white-black, rough, brittle	smooth, green-black, brittle	gray-white-black, rough, brittle

25 From the results of this experiment it is evident that the photochemical polymerization process proceeds faster than thermal polymerization and produces more smooth and uniform polypyrrole films. The thermal polymerization process is obviously different in nature, possibly based on a chemical polymerization mechanism at elevated temperatures, leading to the formation of a partially silver-filled non-conducting polypyrrole matrix.

EXAMPLE 2

5 In order to improve the mechanical properties of PPY films three different electron acceptor salts were investigated: AgNO_3 , AgTs and AgBF_4 . It has been reported that incorporation of tosylate anions improves the mechanical properties of electrochemically formed PPY films. Thus, these three electron acceptor salts were added to photopolymerizable formulations using pyrrole : acceptor molar ratios ranging from 100:1 to 4:1, the latter being closest to the ratio of pyrrole monomer to positive charge found in 10 electrochemically polymerized films. Figure 1 shows the dependence of electrical conductivity on the concentration of electron acceptors (AgNO_3 and AgTs) added to the formulations. Both curves exhibit a maximum conductivity value of approximately 0.1 - 0.3 S cm^{-1} at pyrrole : salt molar ratios between about 3:1 and about 8:1. A steep decrease in conductivity occurred at molar ratios higher than 15:1. In the case of AgTs , at low added salt 15 concentrations, the conductivities were several orders of magnitude lower than those for polymer films photopolymerized with AgNO_3 . The data shown in Figure 1 includes films of different thicknesses, where all of them were photopolymerized and then peeled off from Al substrates. Although the thinner films were less brittle and less fragile, no improvement in mechanical properties was observed for films photopolymerized with tosylates.

20 In experiments performed involving different substrates it was found that comparisons between photopolymerized polypyrrole films were best achieved if polystyrene was used as the substrate, and if the films under investigation were cured at the same time, which assured the same curing conditions. Polystyrene showed satisfactory wettability for a whole range of film compositions used.

25 In Table 2, results are given for PPY films photopolymerized using different silver salts, and their mixtures, added at pyrrole:salt molar ratios of 8:1. All the films yielded conductivity values within an order of magnitude of each other (approximately 0.1 to 0.4 S cm^{-1}), except in the case of AgBF_4 which displayed a conductivity value two orders of magnitude lower. AgBF_4 -containing films possessed the poorest mechanical properties, and

required the longest curing times for complete curing. When mixed with AgNO_3 in equimolar concentrations, but keeping the total pyrrole/salt ratio constant (8:1), the conductivity of polypyrrole films improved and approached the values measured for AgNO_3 alone.

5 From the data presented in Figure 1 and Table 2, it was concluded that AgNO_3 added to photopolymerizable formulations in amounts corresponding to 10 - 15 mol %, provide the necessary electron acceptor properties for photopolymerization to take place, and gives the amount of NO_3^- anions required for charge balance inside the polymer. Thus, AgNO_3 is the optimal choice of electron acceptor for the photopolymerization of pyrrole.

10

TABLE 2. Conductivity of photopolymerized PPY films containing different anions (Electron acceptor: Ag^+ ; Photoinitiator: 3 wt% IRGACURETM 261; pyrrole/salt ratio = 8:1).

15

ELECTRON ACCEPTOR SALT	STAND ALONE FILMS		FILMS ON POLYSTYRENE	
	CONDUCTIVITY S cm^{-1}	THICKNESS μm	CONDUCTIVITY S cm^{-1}	THICKNESS μm
AgNO_3	0.425	62	0.158	34
AgTs	0.197	88	0.179	53
AgBF_4			0.0018	57
$\text{AgNO}_3\text{/AgTs}$	0.212	168		
$\text{AgNO}_3\text{/AgBF}_4$	0.375	51		

20

EXAMPLE 3

25

A series of experiments were performed to examine the electrical resistance of photopolymerized polypyrrole films as a function of monomer/electron acceptor mole ratio in the starting formulation. A mole ratio range of 20:1 to 0.5:1 (pyrrole:silver nitrate) was investigated. The solutions were prepared in one ml of pyrrole monomer and varying amounts of silver nitrate. Pyrrole films of constant thickness (ca. 60 microns) were

produced. A minimum resistance (Van der Pauw method) of about $80\ \Omega$ was observed at a 1:1 mole ratio of monomer to silver nitrate. Results shown in Figure 2 demonstrate that by simple adjustment of the concentration of starting formulation components (monomer and electron acceptor) a change in resistance can be obtained.

5

EXAMPLE 4

10 Simple tests of thick film curing were performed by simultaneous illumination of formulations containing photoinitiators added at 3 wt% to an 8:1 pyrrole:AgNO₃ solution. Exposure to UV light was brought about from the top of miniature glass vials (0.7 cm dia. and 1.1 cm height) containing different photoinitiators. The process of photopolymerization was closely followed under low illumination conditions (corresponding to a temperature of 15 30 - 32 °C), in order to determine the changes taking place during photopolymerization. In all four vials the polymerization process went through different stages which affected the color of the bulk and/or surface layers of the formulations and the speed of solidification. From this simple experiment it was observed that cationic photoinitiators exhibited faster curing rates than radical photoinitiators. Especially, IRGACURE™ 261 demonstrated better 20 curing (in line with weak absorption of 366 nm light), as evidenced by a deeper and more homogeneous blackening and solidification of the entire formulation volume in the glass vial.

25 Although the choice of photoinitiator between triaryl-sulfonium salts and the ferrocinium photoinitiator, all three being cationic photoinitiators, was not conclusive, the ferrocinium photoinitiator is more suitable for photopolymerization of pyrrole because it allows deeper light penetration through the black solidified surface layer. Ferrocinium photoinitiators have been found to be successful for the photopolymerization of epoxides, which have been used in this work as potential copolymers with polypyrrrole.

The effect of ferrocinium photoinitiator concentration on the curing time of PPY

films is shown in Figure 3. Formulations containing increasing amounts of photoinitiator were applied at different thicknesses on aluminum and glass substrates, and were cured simultaneously. Curing time was determined by observing solidification and by the pencil hardness test. Increasing the amount of photoinitiator from 1 to 8 wt% decreased the curing time by approximately a factor of two. Figure 4 shows that increasing amounts of photoinitiator present in the films causes a slight decrease in conductivity.

10 **EXAMPLE 5**

Organic anions tested as film flexibilizing components were DDS (dodecyl sulfate, sodium salt) and DDBS (dodecyl-benzene sulfonate, sodium salt). They were added to the already optimized formulation to yield the highest conductivity, i.e., pyrrole:AgNO₃ ratio of 8:1 and 3 wt% of IRGACURE™ 261 photoinitiator. Amounts added to the formulation are expressed as pyrrole/surfactant molar ratios. Polypyrrole films were photopolymerized from these formulations under different illumination conditions and on various substrates. A post-cure thermal treatment at the highest lamp radiance was applied after photocuring. This is recommended by Ciba-Geigy for completion of curing processes when IRGACURE™ 261 photoinitiator is used.

20 Photopolymerization along the area of the substrate covered by the formulation was followed by observing black solidifying zones smoothly spreading across the surface of the substrate. It was evident that these additives helped diffusion of polymerizing components in the thin formulation layer. Curing was generally slower than for the films without surfactant additives. Films obtained showed a significant improvement in mechanical properties. They were very flexible compared to the films that did not contain surfactant additives. It was possible to bend these films, whether coated on an aluminum sheet or on polystyrene, through angles greater than 90° without breaking them. Additives acting as surfactants greatly improved the adherence of the film to the substrate. More importantly, films so formulated retained good conductivity. DDBS was less soluble in pyrrole and gave

rise to films of lower flexibility when compared to films with DDS as an additive. Table 3 compares conductivities for DDS- and DDBS-containing films, added as pyrrole:surfactant molar ratios of 15:1.

5

10 **TABLE 3.** Conductivity of photopolymerized PPY films with large organic anions as flexibilizers (Pyrrole/AgNO₃ = 8:1; Pyrrole/surfactant = 15:1; photoinitiator: 3 wt% IRGACURETM 261; Curing time: fast, 1.9 W cm⁻² with thermal post-cure: 2.3 W cm⁻²).

15

20

ADDITIVE	DDS		DDBS	
	SUBSTRATE MATERIAL	CONDUCTIVITY S cm ⁻¹	THICKNESS μm	CONDUCTIVITY S cm ⁻¹
STAND ALONE	0.21	163	0.20	215
STAND ALONE	0.51	61	0.59	75
STAND ALONE PY/AgNO ₃ =5/1	0.134	224		
POLYSTYRENE	0.48	39	0.32	62
POLYMER FILM APPEARANCE	smooth, black, curing time: 1.3 min/layer, very flexible		smooth, black, curing time: 2 min/layer, flexible	

25

Figures 5 and 6 show variations in curing time and conductivity of films photopolymerized with different concentrations of DDS additive. It was possible to follow the curing progress at two stages: corresponding to surface solidification and when curing was completed. Both plots exhibit the same slope, showing that the curing time is longer with increasing amounts of DDS in the films. Films with higher concentrations of surfactant additive became soft. The electrical conductivity of the films was within the range 0.1 - 0.5 S cm⁻¹. Minimum electrical conductivity, evident at ratios between 30:1 to 50:1, is probably due to an artifact in that the resistivity probe tips penetrated into the soft films at ratios

greater than 30:1 and hence, displayed conductivity values higher than those for the films of measured thickness. It was found that films containing between 10:1 and 20:1 of pyrrole:DDS additive, possess the greatest flexibility and conductivity.

5

EXAMPLE 6

10 A series of experiments were performed to examine the electrical resistance of polymer films photopolymerized from mixtures of pyrrole and aniline monomers. Solutions of silver nitrate (AgNO_3), pyrrole, and aniline were prepared in one ml of acetonitrile. Equivalent molar amounts of AgNO_3 and various proportions of pyrrole and aniline were prepared in a large volume excess of acetonitrile (about 500 volume percent).

15 The solutions were deposited with a brush to coat a masked ceramic alumina substrate and cured immediately. Two to three successive layers were built up on the alumina with a thickness between 20 and 160 microns. The polymer samples were cured in 1 sq cm areas and contacts for resistance measurements were drawn with a silver paint. Resistivity (Ω^{cm}) was calculated for each polymer film prepared in duplicate by the van der Pauw method. Figure 7 shows the relationship between the pyrrole/aniline monomer ratio and resistivity 20 of the resulting films.

25 The results show that the presence of a comonomer in the photopolymerization formulation can be utilized to change and/or control the resistance of the resulting mixed conducting polymer film. A maximum in resistance was obtained in the molar ratio range between about 35 and about 70 percent (%) of aniline present in the formulation. At higher aniline ratios (> 70%), the resistance decreased. The lowest resistances were found for films with little or no aniline present. However, polymer films with aniline present in the formulation exhibited smoother film surfaces. The same results were obtained using fiber-glass epoxy and polyimide PWB substrates.

EXAMPLE 7

5 A series of experiments were performed under the conditions described in Example 5, for various copolymer materials such as an aqueous acrylic resin, bisphenol A diglycidyl ether, and perfluorinated sulfonic acid. The results are given below in Table 4.

10 TABLE 4. Conductivity of PPY films photo-copolymerized with different resins (pyrrole /AgNO₃ = 8:1; photoinitiator: 3 wt% IRGACURE™ 261; curing: different conditions; average 1.2 W cm⁻²; for araldite 2.1 W cm⁻² and thermal postcure at 2.3 W cm⁻²).

COPOLYMER MATERIAL	% (w/w) OF COPOLYMER	THICKNESS μm	CONDUCTIVITY S cm ⁻¹	COMMENT
MAINCOTE HG 54 D	50 (1:1)			no polym., yellow precipitate
	4	65	0.074	black, smooth,
ARALDITE 502 (polystyrene) (on glass)	4	119	0.072	max.copol.conc = 4 wt%
	10	121	0.086	black, smooth, flexible
	14	74	0.022	longer curing needed
	20	159	0.0092	at high lamp power
	14	41	0.063	$t > 10-15 \text{ min/layer}$
	20	20	0.044	-
	34	14	0.015	-
	51	12	0.0068	-
NAFION	5	64	0.53	black, smooth, flexible
	10			too resistive, voltage transients show saturation

15 The waterborne acrylic resin did not undergo successful copolymerization with pyrrole. It was possible to make a film only if it was added at amounts less than 4 wt%, however, resulting in reduced conductivity. Acrylic resins undergo very little cationic 20 polymerization (mostly radical induced), which is incompatible with the photo-polymerization of pyrrole.

25 Copolymerization of pyrrole with bisphenol A diglycidyl ether, which undergoes a cationic photopolymerization mechanism, resulted in good films covering a large range of pyrrole/copolymer ratios from 10:1 to 1:1. It may be noted that on using the ferrocinium

photoinitiator and bisphenol A diglycidyl ether alone, a yellow nonconducting film was obtained. Conductivities of PPY/epoxide copolymers were approximately an order of magnitude lower than that of PPY films without a copolymer. Increasing the amount of epoxy copolymer up to a ratio of 1:1 resulted in an order of magnitude decrease in conductivity as shown in Table 4. PPY/epoxide copolymers possessed good flexibility and exhibited softness, the latter increasing when higher amounts of epoxide copolymer were added. Also, these films adhered very well to metallic and nonmetallic substrates, and it was difficult to peel them off, partly due to their softness.

Photocopolymerization with relatively low concentrations of perfluorinated sulfonic acid appeared to be successful, and high electronic conductivities were retained. At higher concentrations of Nafion copolymer (10 wt%), the conductivity values were unobtainable and decreased, indicating a structure of mixed conducting pyrrole and nonconducting (or ionically conducting) Nafion.

15 EXAMPLE 8

A test was performed using a high resolution laser and an electron-beam for the patterning of conducting polypyrrole lines.

Referring now to Figure 8, alumina substrates, (bottom row, one inch by one inch substrates), have laser patterned lines formed from a 4:1 pyrrole:silver nitrate formulation spun at 500, 300, and 1000 RPM, respectively. Each alumina substrate contains several sets of 3-5 lines obtained with a different number of laser beam passes. Alumina substrates shown in the top row (one inch by one inch substrates) have laser patterned lines using an 8:1 pyrrole:silver nitrate formulation spun at 500 and 1000 RPM, respectively. The small alumina substrate has a patterned line formed from a 4:1 pyrrole:silver nitrate formulation photopolymerized by a 10 nm wide electron beam. Each of the formulations contained acetonitrile.

The parameters (beam current, beam sweep rate, number of passes) were varied for each set of exposures to test the photopolymerization process. Line widths obtained using

argon ion laser imaging were about 100 microns.

An electron beam was used to fabricate both narrow lines (down to 1.5 microns wide) and wide lines (about 80 microns wide) (See Figure 8), using the same exposure parameters, but two different techniques. The narrow lines were fabricated using a step and repeat 5 technique, (i.e. the electron beam was moved across the sample and the sample moved between exposures) to form a number of parallel lines with approximately equal line widths and spacing. The wide lines were fabricated by exposing narrow lines together (side by side), with sufficient overlap to eliminate any visible rastering under SEM examination.

10

EXAMPLE 9

Scanning electron micrographs of fracture surfaces of thick photopolymerized (70 15 microns) and electropolymerized (67 microns) polypyrrole films are shown in Figure 9. It can be seen from Figure 9(a) that electrochemically prepared polypyrrole is dense, non-fibrillar and volume-filling. The photopolymerized polypyrrole material of Fig. 9(b) is surprisingly compact, but more open-structured and contains some voids.

Scanning electron micrographs at two magnifications of the outer surfaces of 20 electropolymerized and photopolymerized polypyrrole films are presented in Figure 10. Now referring to Figures 10(a) and 10(c), an electrochemically prepared polypyrrole is shown to have nodular or "cauliflower" structures that are consistent with a nucleation/dendritic film growth mechanism. This surface topology is frequently observed for electrochemically prepared polypyrrole materials. In contrast, the surface topography for 25 the photopolymerized polypyrrole films shown in Figures 10(b) and 10(d) was rather featureless, being smooth and flat. As observed in the micrograph of the fractured surface of photopolymerized PPY in Figure 9(b), a large number of evenly distributed silver metal grains of surprisingly uniform size can be seen also on its outer surface. In the higher magnification electron micrograph Figure 10(d), the bright, reflective, spherical Ag particles

were determined to be 1 μm or less in diameter. Also in this micrograph, the microporous structure of the photopolymerized film can be clearly seen. For both polypyrrole film types, the surfaces adhering to the substrates were smooth, shiny and featureless.

5

APPLICATION OF PHOTOPOLYMERIZED CONDUCTING POLYMERS TO FORM PASSIVE ELECTRONIC ELEMENTS

The resistivity of electronically conducting polymer lines, such as those shown in Figure 8, can be controlled by the concentration or type of dopant anions from an electron acceptor salt (See Figures 1 and 2) or the concentration and type of copolymers present in the starting formulation (See Figure 7). Whereas varying the concentration of either component in a formulation can effect resistivity, it is preferred that the pyrrole:comonomer ratio in the formulation, particularly the pyrrole:aniline ratio, be optimized to provide a conducting polymer with good adhesion and smoothness on the substrate. The preferred copolymer is aniline and the preferred pyrrole:aniline mole ratios are between about 1 and about 100. It is also preferred that the concentration of electron acceptor salts including the dopant anions in the formulation be used to determine the approximate resistivity of the electronically conducting polymer lines produced upon photopolymerization of the formulation.

20

The overall resistivity of an electronically conducting polymer resistor is a function of the resistivity of the photopolymerized formulation as well as the thickness, width and length of the resistor. A plurality of resistors can be formed on a common substrate, where the resistors have various overall resistances on the order of about 10 ohms (Ω) to about 10 $\text{M}\Omega$. One preferred method for forming resistors with various resistances in a single layer on a substrate involves the preparation of a plurality of formulations having different concentrations of the electron acceptor salt. Each formulation can be used to form resistors having resistances within a certain range. Increasing the electron acceptor salt concentration, such as AgNO_3 , increases the conductivity and decreases the resistivity of the photopolymerized conducting polymer. For example, a first formulation might be used to

form about 10-100 Ω resistors and two more formulations might be used to form about 100 - 10,000 Ω and about 10K Ω - 10 M Ω resistors, respectively. Only one formulation is applied, dried and photopolymerized at a time. Each individual formulation is spin-coated onto the substrate to form a film having substantially uniform thickness. After allowing time for the formulation to dry, select areas or lines are photopolymerized using any of the techniques previously described, e.g., masked UV light, laser light, or electron beams. The unpolymerized formulation is then washed from the substrate surface by a suitable solvent. Since the thickness of the resistor lines are substantially uniform, due to the spin-coating of the formulation, and the length of the resistor must span between two conductor contact points, it is preferred that the width of the resistor be varied to achieve a desired resistance.

It is preferred that the width of each resistor be established by photopolymerizing resistor lines having a width that will form the desired resistance. However, because the photopolymerization process may form lines having sides that are not entirely uniform or smooth, it may be difficult to obtain resistors having resistances within narrow tolerances without further processing.

After the resistors have received a post thermal cure, the overall resistance of a resistor may be increased by reducing the width of the resistor line through laser trimming. Therefore, in applications where a precise resistance is necessary or desirable, it is preferred to photopolymerize a resistor line having a width slightly greater than is needed to achieve the desired resistance, thereby forming a resistor having a resistance lower than desired, and then trim the width of the resistor with a laser until the resistance increases to the desired value.

After all the resistors having resistances within the first formulation's useful range have been formed, additional formulations may be used to obtain resistors within other ranges. Any number of formulations may be applied in this manner having wide or narrow resistance ranges.

Therefore, the preferred method of forming a plurality of resistors having various resistances involves spin-coating, drying, photopolymerizing and washing a first

formulation, then repeating these steps for each remaining formulation. Only after all resistors have been photopolymerized will they receive a single thermal cure and each of the resistors, regardless of formulation, will be laser trimmed to a specific resistance.

5 CAPACITORS

It is believed that solid electrolytic capacitors, in which an electronically conducting polymer is applied as an electrolyte, could be fabricated that would exhibit good frequency and thermal stability characteristics. The conducting polymers could be photopolymerized on the surface of dielectric materials, such as etched or anodized aluminum and tantalum, to form a solid state electrolytic capacitor in which a conductive polymer is applied as an electrolyte.

For example, a process for forming a solid state electrolytic capacitor might comprise the steps of applying a thin film of a formulation on a dielectric layer; photopolymerizing a portion of the film; removing the unpolymerized portion of the film from the substrate with a solvent; depositing a layer of palladium onto the surface of photopolymerized polymer by immersion in solution consisting of a palladium containing salt; and electrodepositing a layer of a metal conductor such as gold, copper or platinum on palladium precoat.

20

INDUCTORS

Flat spiral inductors made by printing or defining conductor patterns directly onto a substrate exhibit relatively low Q factors and also, since inductance is directly proportional to the overall size and the number of turns, require extensive substrate area to achieve high values. However, the methods disclosed above can be used to form three-dimensional, high inductance inductors, as shown in Figure 14, by the photopolymerization of a conducting polymer in vertical paths through a dielectric layer. The preferred method of forming three-dimensional inductors comprises the steps of: (i) photopolymerizing a conducting

polymer on a substrate with subsequent metallization, (ii) deposition of a dielectric layer whether by photopolymerization or other means, (iii) drilling holes (on the order of about 250 μm and smaller) in the dielectric layer by laser ablation, (iv) simultaneous photopolymerization of the through-holes and conducting lines on the top of the dielectric layer, and (v) metalization of the conducting polymer vias (both through-holes and conducting lines. (See Figures 12 and 13.) The deposition of conducting polymers on through-hole walls can be achieved by coating the walls with a layer of photopolymerizable material (See Figure 13), preferably in the same step that the material is coated on the top surface of the dielectric material. It is also preferred that the photopolymerization of the through-holes and conducting polymers on the top surface be carried out simultaneously.

Spontaneous deposition of noble metals, e.g. palladium (Pd) and silver (Ag), onto polypyrrole occurs simply by immersing the substrate in an aqueous solution containing the corresponding metal salt. It may also be possible to spontaneously deposit gold (Au), and other metals on photopolymerized polypyrrole. The preferred noble metal is palladium. While palladium may be used with any Pd^{2+} salt, (i.e. Pd Br_2 , PdCl_2) the most preferred metal salt is palladium bromide.

The ease with which conducting polymer-based passive elements can be mounted on PWB and MCM substrates using computer controlled lasers reduces the time and expense of producing prototype quantities of passive elements, PWBs, and MCMs. An additional benefit of this technique is that laser trimming for active circuit adjustment even at the MCM level is easily attainable. Thus, the passive elements, particularly the resistor values, can be customized to desired specifications even after the circuit, on MCMs or PWBs, has already been assembled and the components mounted.

The methods of the present invention may be used alone or in combination with other technology for forming multichip modules. Specifically, it is anticipated that the passive elements of the present invention may be incorporated into integrated circuits formed primarily using thin film or thick film technologies. For example, a specific circuit may be optimized by using a resistor according to the present invention. The remainder of the integrated circuit, including logic elements, conductive lines and the like, may be formed on

a substrate using chemical vapor deposition (CVD) and physical vapor deposition (PVD). The integrated circuit is formed layer by layer until the resistor is needed. The underlying layer will preferably provide a pair of conductive leads on which the resistor is formed. Following formation of the resistor, the surface of the substrate may be planarized and the resistor covered by conventional dielectric chemical vapor deposition (DCVD). Formation of integrated circuits may continue on the same or subsequent layers.

5 It will be understood that certain combinations and subcombinations of the invention are of utility and may be employed without reference to other features in subcombinations. This is contemplated by and is within the scope of the present invention. As many possible 10 embodiments may be made of this invention without departing from the spirit and scope thereof, it is to be understood that all matters hereinabove set forth or shown in the accompanying drawings are to be interpreted as illustrative and not in a limiting sense.

1 WHAT IS CLAIMED IS:

- 1 1. A method of forming a passive element on a conducting or nonconducting substrate surface comprising the steps of:
 - 3 (a) applying a thin film of a formulation comprising pyrrole monomer and a salt onto the substrate surface, wherein the salt consists of an electron acceptor containing Ag⁺ cations and a dopant anion selected from the group consisting of NO₃⁻, NO₂⁻, BF₄⁻, ClO₄⁻ and tosylate;
 - 7 (b) photopolymerizing a portion of the film to form a passive element; and
 - 8 (c) removing the unpolymerized portion of the film from the substrate with a solvent.
- 1 2. The method of claim 1 wherein the pyrrole:salt molar ratio in the formulation is greater than about 0.5, and wherein the passive element has an electrical resistance substantially determined by the molar concentration of the salt in the formulation.
- 1 3. The method of claim 1 wherein the pyrrole:salt molar ratio in the formulation is between about 0.5 and about 20, and wherein the passive element has an electrical resistance substantially determined by the molar concentration of the salt in the formulation.
- 1 4. The method of claim 1, 2 or 3 wherein the formulation further comprises a comonomer, and wherein the pyrrole:comonomer molar ratio is between about 1 and about 100.
- 1 5. The method of claim 4 wherein the comonomer is aniline.
- 1 6. The method of any one of claims 1 to 5 wherein the film further comprises a photoinitiator.
- 1 7. The method of any one of claims 1 to 6 wherein the film further comprises a

2 surfactant.

1 8. The method of any one of the preceding claims wherein the formulation further
2 comprises a solvent, and the method further comprises the step of allowing a substantial
3 amount of the solvent to evaporate from the film before photopolymerizing.

1 9. The method of any of the preceding claims wherein further comprising the step of
2 heating the passive element to provide a post-thermal cure at a temperature of between about
3 25 and about 100 degrees Celsius for between about 0.1 and about 3 hours.

1 10. The method of any of the preceding claims wherein the passive element is a resistor,
2 and further comprising the step of:
3 (d) increasing the overall resistance of the resistor by trimming the resistor with a
4 laser.

1 11. The method of claim 10 further comprising the step of:
2 (e) measuring the overall resistance of the polypyrrole resistor; and
3 (f) repeating steps (d) and (e) until a desired overall resistance is obtained.

1 12. The method of any of the preceding claims wherein the film is selectively
2 photopolymerized by direct laser imaging.

1 13. The method of claim 12 wherein the laser light has a wavelength between about 457
2 and about 1060 nanometers.

1 14. The method of claim 12 or 13 further comprising the steps of:
2 directing the laser light through a condensing lens to form a beam having a width of
3 about 150 micrometers; and
4 rastering the beam to photopolymerize a specified area of the film.

1 15. The method of any one of claims 12 to 14 wherein direct laser imaging is performed
2 using a continuous wave argon-ion laser operating at a beam power of between about 300
3 and about 400 milliwatts; and wherein the beam is moved at a linear velocity of between
4 about 2 and about 16 millimeters per minute.

1 16. The method of any one of the preceding claims wherein the film is selectively
2 photopolymerized by an electron beam.

1 17. The method of any one of the preceding claims wherein the film is applied by spin
2 coating at between about 250 and about 2,000 rotations per minute.

1 18. A method of forming a plurality of electronically conducting polymer resistors
2 having different electrical resistances on a common substrate surface, the method comprising
3 the steps of:

4 (a) preparing a plurality of formulations comprising a monomer and a salt, wherein
5 the salt consists of an electron acceptor consisting of Ag^+ cations and a dopant anion selected
6 from the group consisting of NO_3^- , NO_2^- , BF_4^- , ClO_4^- and tosylate, and wherein each of the
7 formulations has a different molar concentration of salt for forming resistors having
8 resistances within a given range;

9 (b) applying a thin film of a formulation onto the substrate surface;

10 (c) photopolymerizing a portion of the film to form a resistor, wherein the
11 photopolymerized portion extends between two contact points and has sufficient thickness
12 and width so that the overall electrical resistance between the two contact points is somewhat
13 less than a resistance specified for that resistor;

14 (d) removing the unpolymerized portion of the film from the substrate with a
15 solvent;

16 (e) repeating steps (b) through (d) for each of the plurality of formulations;

17 (f) heating the resistors to provide a thermal cure;

18 (g) measuring the overall resistance of a resistor; and
19 (h) increasing the overall resistance of the resistor up to a specified resistance by
20 trimming the resistor with a laser;
21 (i) repeating steps (g) and (h) until each resistor has an overall resistance near the
22 resistance specified for that resistor.

19. The method of claim 18 wherein the monomer is pyrrole and the salt is silver nitrate.

2

1 20. A method of forming an electronically conducting polymer inductor on a
2 nonconducting substrate surface comprising the steps of:

3 (a) preparing a formulation comprising a monomer and a salt, wherein the salt
4 consists of an electron acceptor consisting of Ag^+ cations and a dopant anion selected from
5 the group consisting of NO_3^- , NO_2^- , BF_4^- , ClO_4^- and tosylate;

(b) applying a thin film of the formulation onto the substrate surface;

7 (c) photopolymerizing a plurality of lower horizontal lines in the film;

8 (d) removing the unpolymerized portion of the film from the substrate with a
9 solvent;

10 (d) depositing a layer of dielectric material over the lower horizontal lines, wherein
11 the layer forms a top surface;

12 (e) drilling holes downward through the layer of dielectric material and into each end
13 of each lower horizontal lines;

14 (f) applying a thin film of the formulation to the holes and top surface of the
15 dielectric material; and

16 (g) selectively photopolymerizing the film to form vertical vias and upper horizontal
17 lines, wherein the ends of each upper horizontal line connect with the vertical vias, and
18 wherein the upper horizontal lines, lower horizontal lines and vertical vias are electronically
19 conducting and cooperate to form a coil-like pathway.

1 21. A method of forming a solid state electrolytic capacitor in which a conducting

2 polymer is applied as an electrolyte comprising the steps of:

3 (a) applying a thin film of a formulation on a dielectric layer;

4 (b) photopolymerizing a portion of the film;

5 (c) removing the unpolymerized portion of the film from the substrate with a

6 solvent;

7 (d) depositing a layer of palladium onto the surface of the photopolymerized

8 polymer by immersion in a solution consisting of a palladium containing salt; and

9 (e) electrodepositing a layer of a metal conductor such as gold, copper or

10 platinum, on the palladium layer.

1 22. A method of forming a plurality of passive elements on a common substrate surface

2 comprising the steps of:

3 (a) preparing a formulation comprising a monomer and a salt, wherein the salt

4 consists of an electron acceptor consisting of Ag^+ cations and a dopant anion selected

5 from the group consisting of NO_3^- , NO_2^- , BF_4^- , ClO_4^- and tosylate;

6 (b) forming an electronically conducting polymer resistor on a conducting or

7 nonconducting substrate surface comprising the steps of:

8 (i) applying a thin film of the formulation onto the substrate surface;

9 (ii) photopolymerizing a portion of the film to form a resistor; and

10 (iii) removing the unpolymerized portion of the film from the substrate with

11 a solvent;

12 (c) forming a solid state electrolytic capacitor in which a conducting polymer is

13 applied as an electrolyte comprising the steps of:

14 (i) applying a thin film of the formulation on a dielectric layer;

15 (ii) photopolymerizing a portion of the film;

16 (iii) removing the unpolymerized portion of the film from the substrate with

17 a solvent;

18 (iv) depositing a layer of palladium onto the surface of photopolymerized

19 polymer by immersion in a palladium salt solution; and

20 (v) electrodepositing a layer of a metal conductor such as gold, copper or
21 platinum, on the palladium layer; and

22 (d) forming an electronically conducting polymer inductor on a nonconducting
23 substrate surface comprising the steps of:

24 (i) applying a thin film of the formulation onto the substrate surface;

25 (ii) photopolymerizing a plurality of lower horizontal lines in the film;

26 (iii) removing the unpolymerized portion of the film from the substrate with
27 a solvent;

28 (iv) depositing a layer of dielectric material over the lower horizontal lines,
29 wherein the layer forms a top surface;

30 (v) drilling holes downward through the layer of dielectric material and into
31 each end of each lower horizontal lines;

32 (vi) applying a thin film of the formulation to the holes and top surface of the
33 dielectric material; and

34 (vii) selectively photopolymerizing the film to form vertical vias and upper
35 horizontal lines, wherein the ends of each upper horizontal line connect with
36 the vertical vias, and wherein the upper horizontal lines, lower horizontal
37 lines and vertical vias are electronically conducting and cooperate to form a
38 coil-like pathway.

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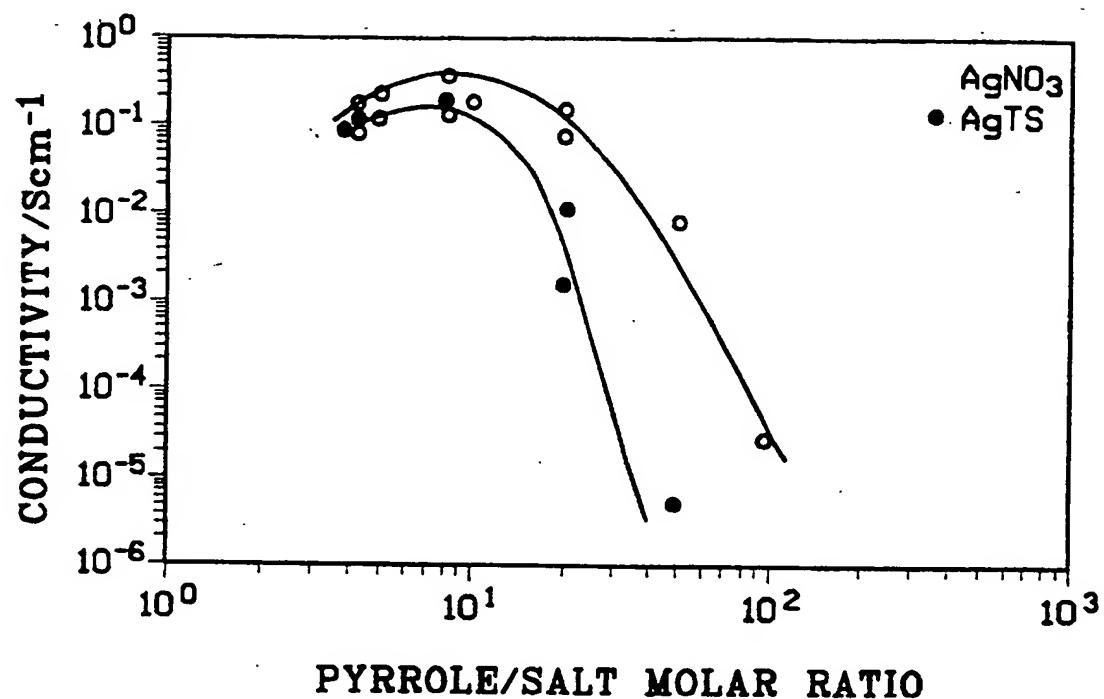


FIG. 1

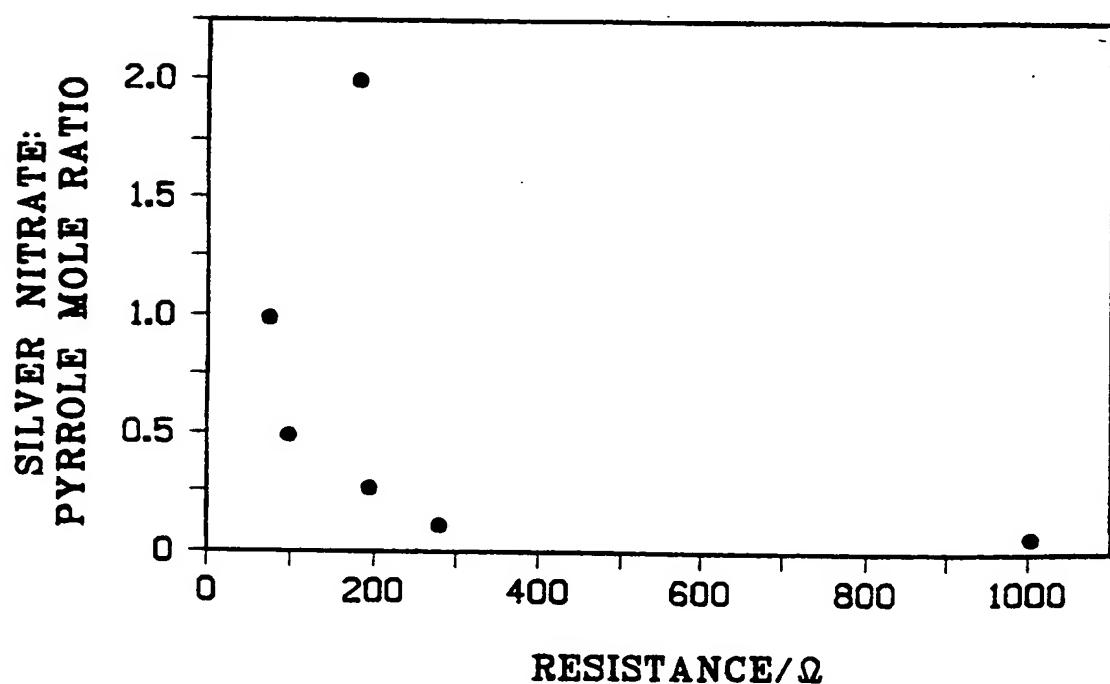


FIG. 2

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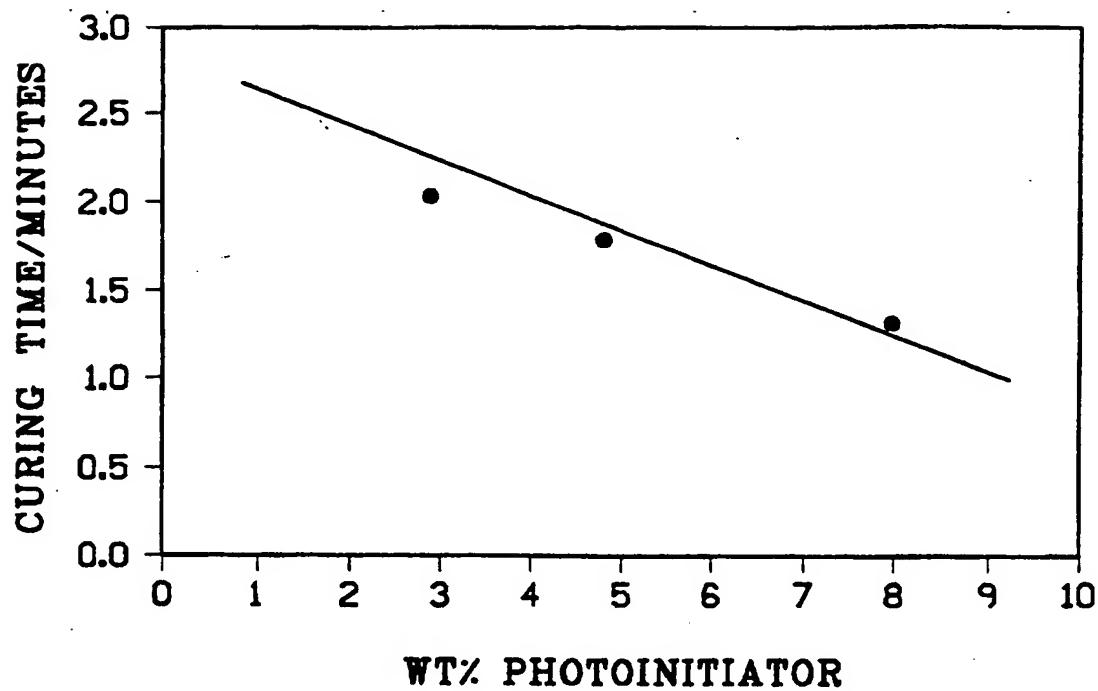


FIG. 3

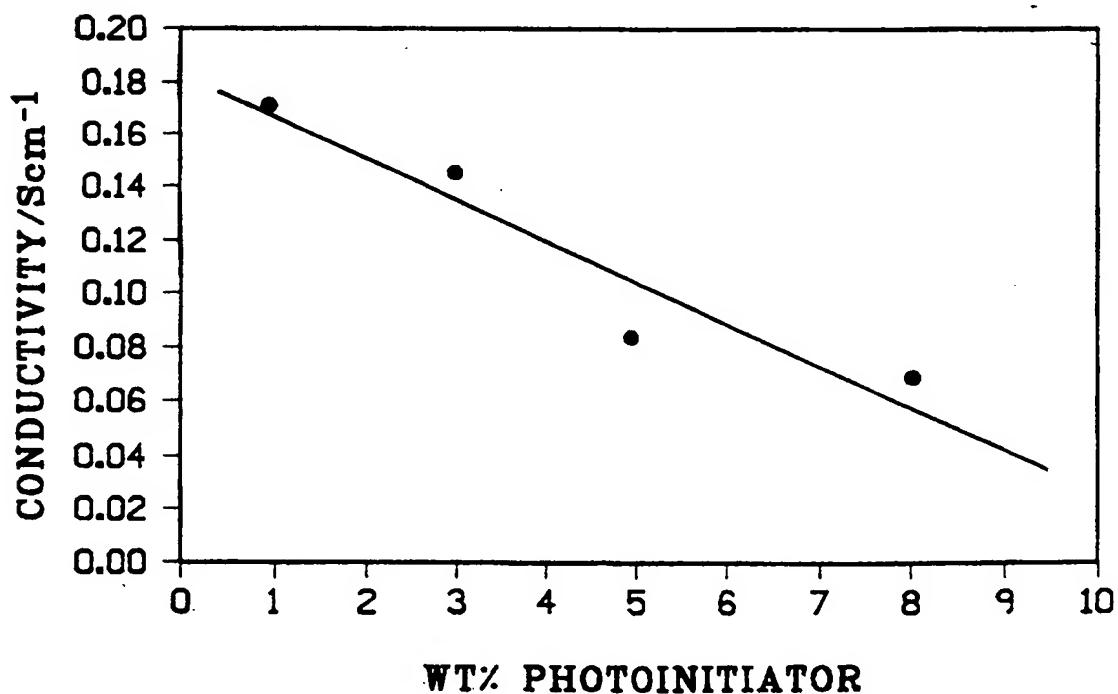


FIG. 4

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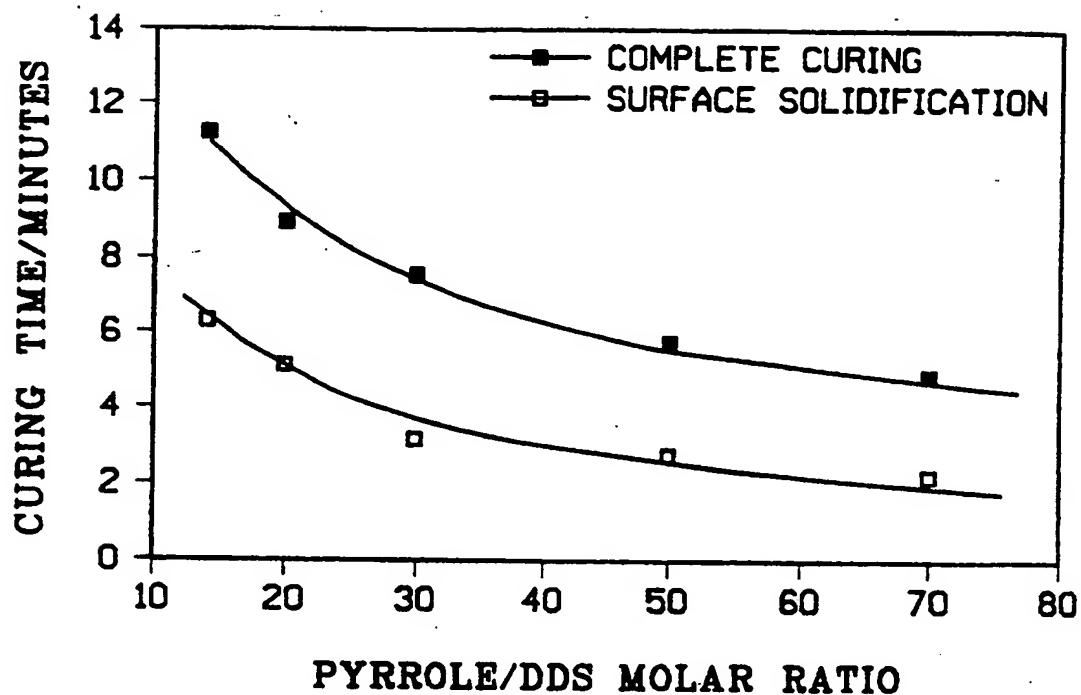
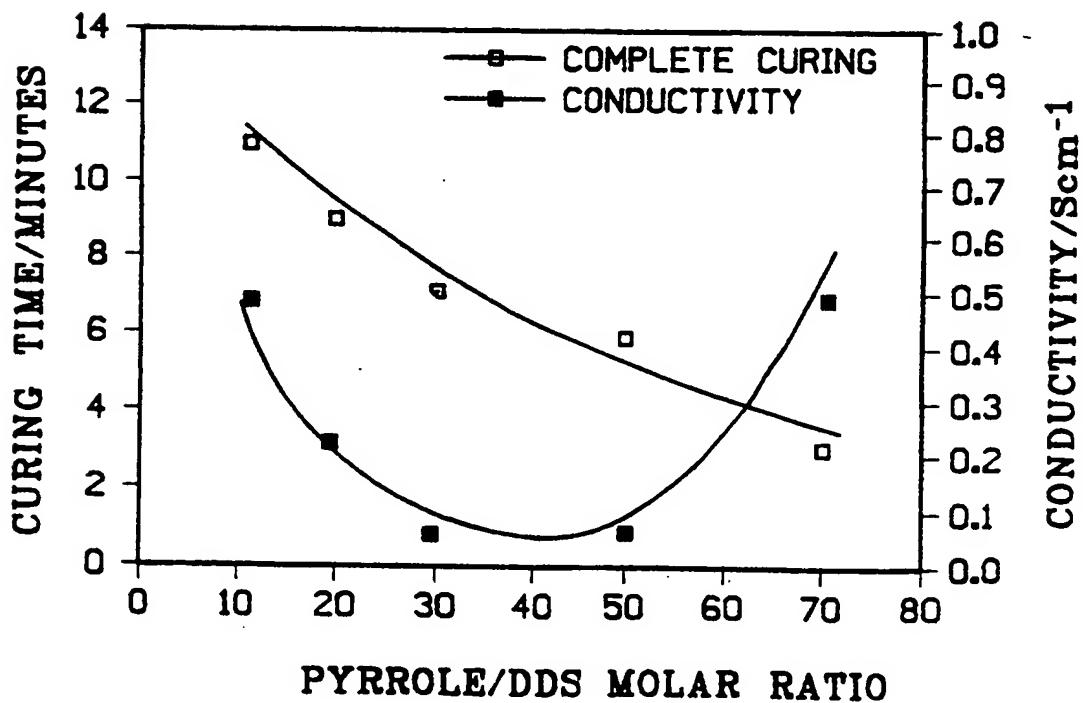


FIG. 5



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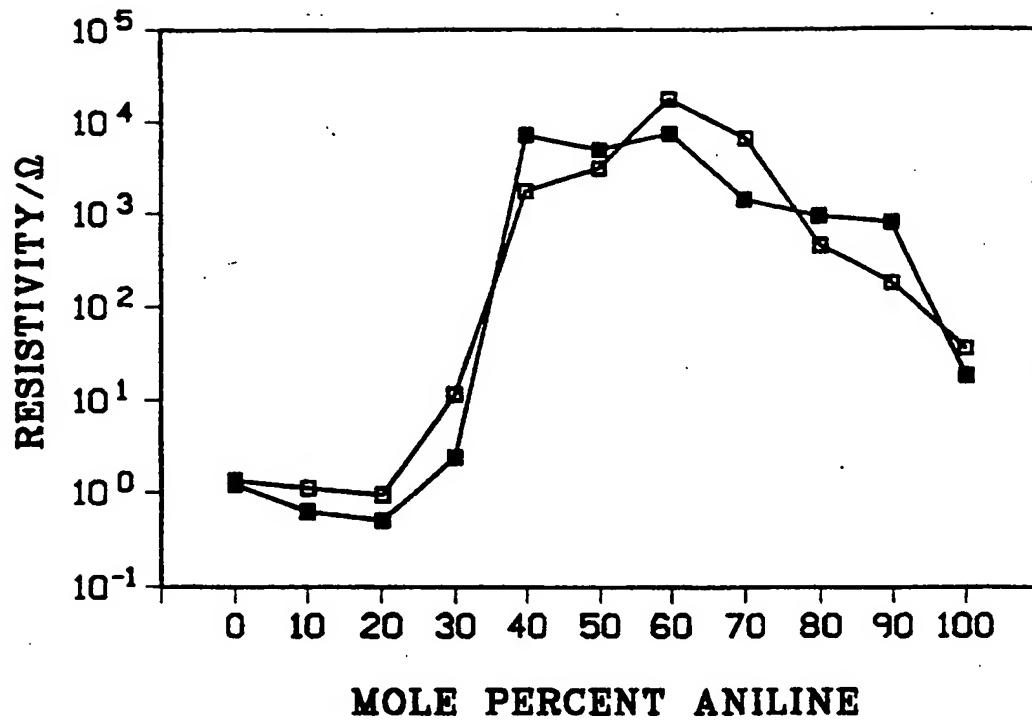


FIG. 7

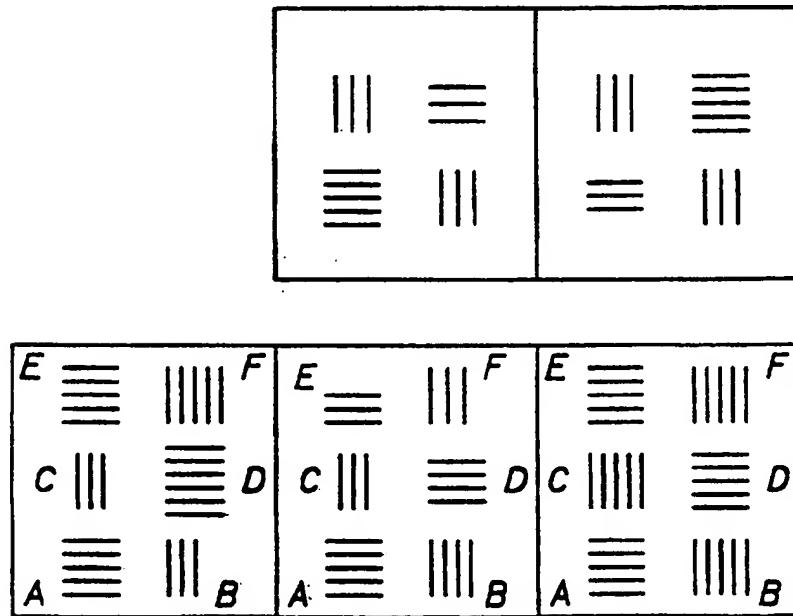


FIG. 8

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POLYPYRROLE



FIG. 9A

POLYPYRROLE

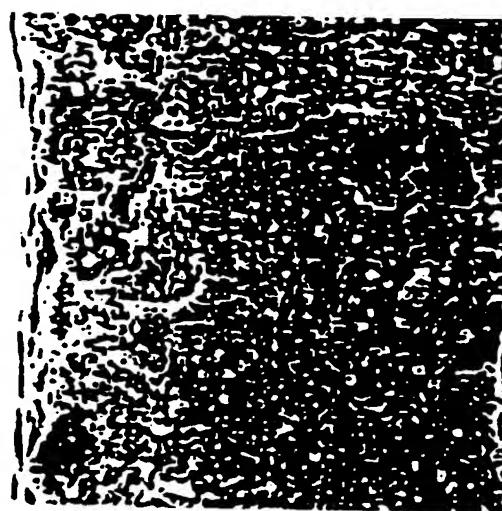


FIG. 9B

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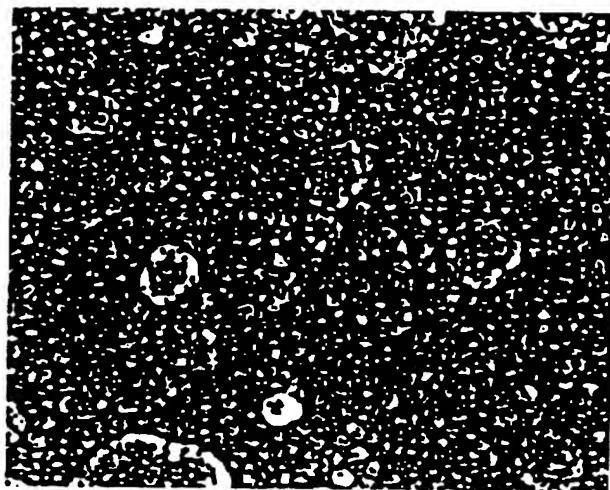


FIG. 10A

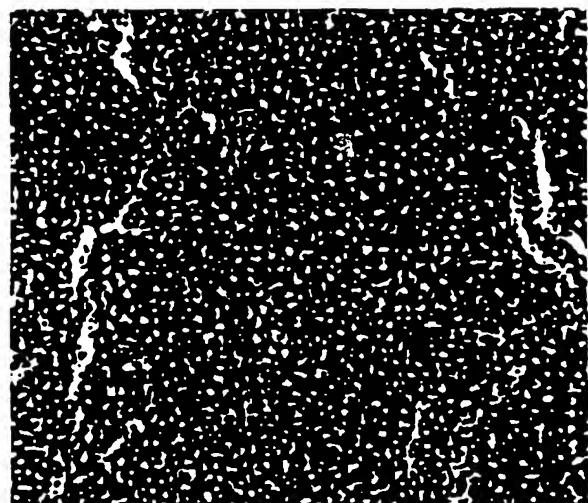


FIG. 10B
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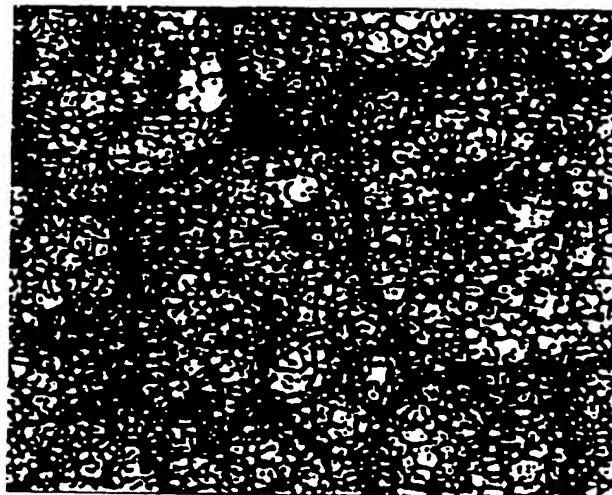


FIG. 10C

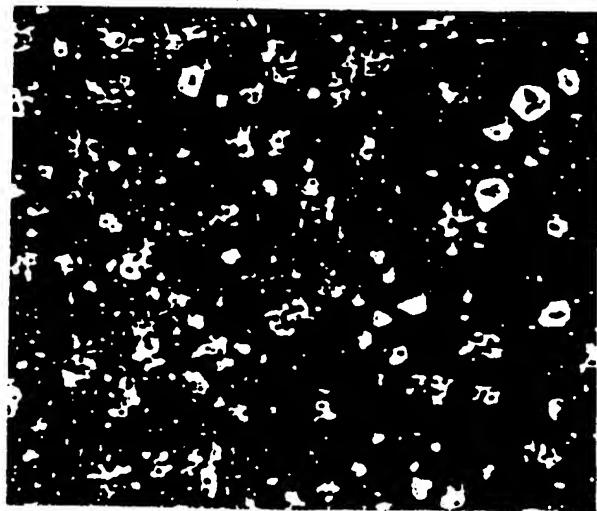


FIG. 10D
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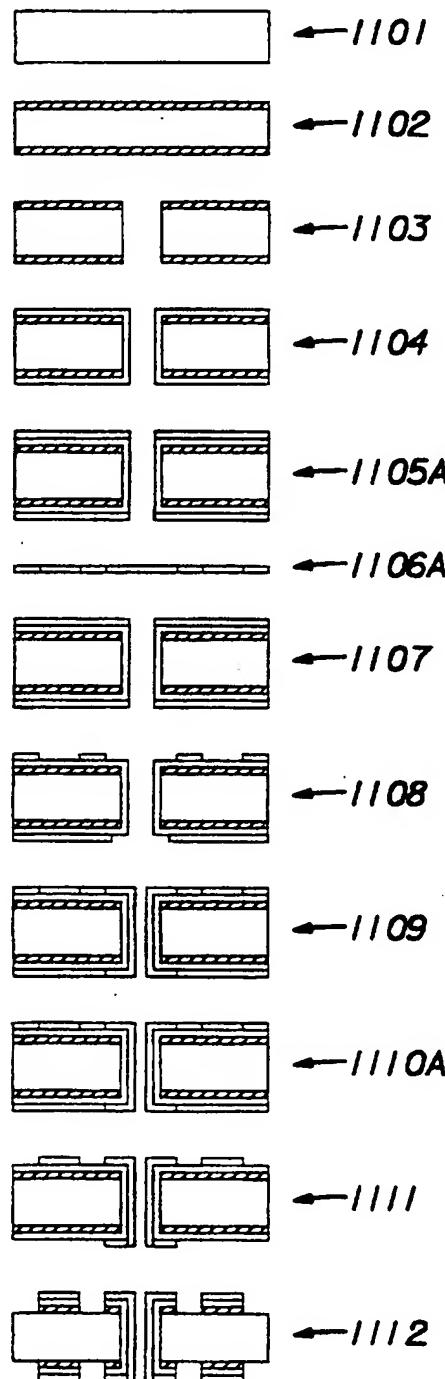
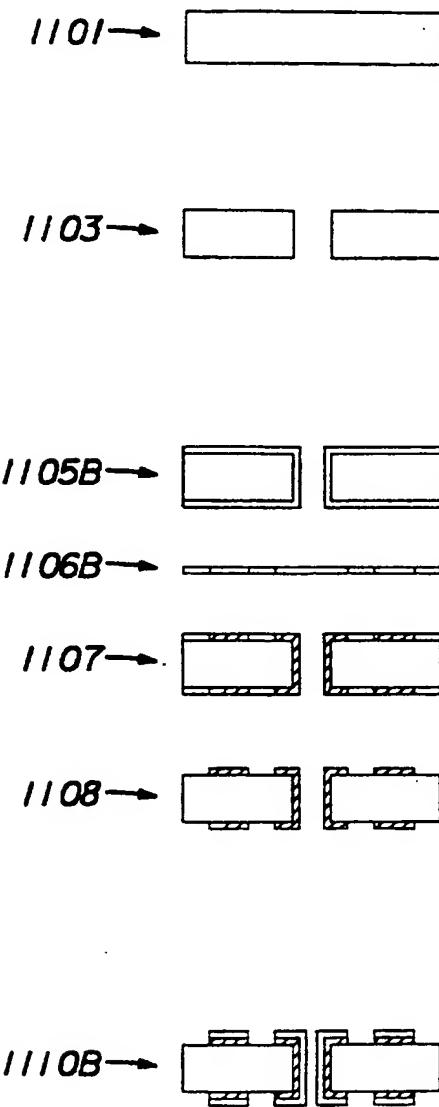
CONVENTIONAL SUBTRACTIVE
PROCESS OF PWB FABRICATIONPWB FABRICATION BASED ON
PHOTOPOLYMERIZATION OF
CONDUCTING POLYMERS

FIG. 11
SUBSTITUTE SHEET (RULE 26)

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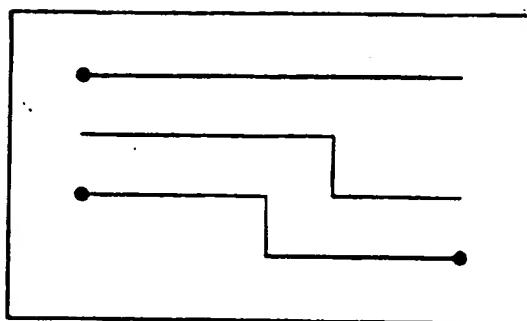


FIG. 12

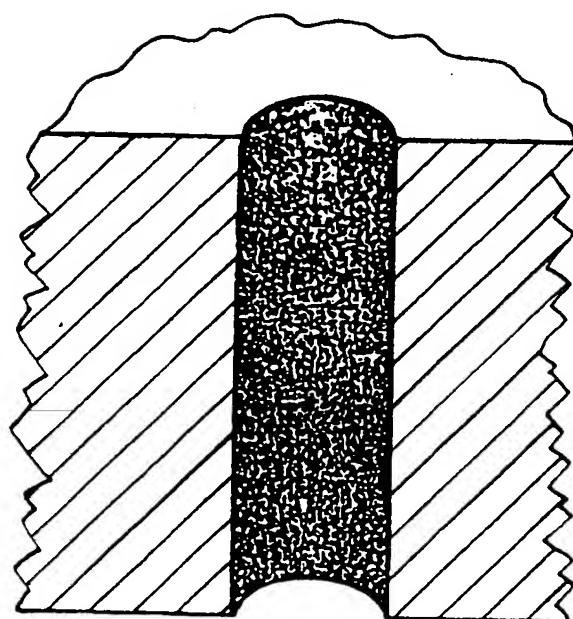


FIG. 13

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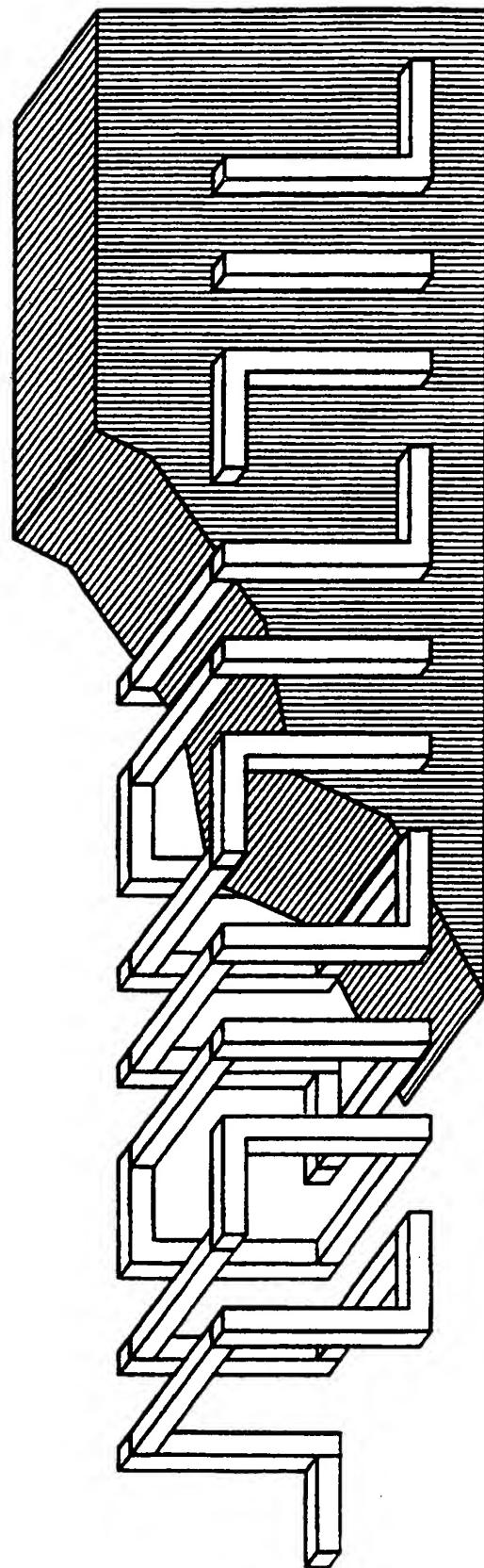


FIG. 14

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INTERNATIONAL SEARCH REPORT

International Application No
PCT/US 97/06047

A. CLASSIFICATION OF SUBJECT MATTER
IPC 6 G03F7/027 H05K1/16 H01G9/02

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)
IPC 6 G03F H05K H01G

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practical, search terms used)

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category *	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
P, X	US 5 545 308 A (O.J. MURPHY ET AL.) 13 August 1996 see claims ---	1-17
A	WO 94 02886 A (DSM N.V.) 3 February 1994 see page 3, line 37 - line 39 see page 4, line 1 - line 22 see page 8, line 15 - line 17; example 1 ---	1-22
A	DATABASE WPI Section Ch, Week 8925 Derwent Publications Ltd., London, GB; Class A35, AN 89-183669 XP002036976 & JP 01 123 228 A (SHINGIJUTSU KAIHATSU KK), 16 May 1989 see abstract ---	1-22
	-/-	

Further documents are listed in the continuation of box C.

Patent family members are listed in annex.

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- *'&' document member of the same patent family

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Date of the actual completion of the international search

6 August 1997

Date of mailing of the international search report

22.09.97

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INTERNATIONAL SEARCH REPORT

International Application No
PCT/US 97/06047

C.(Continuation) DOCUMENTS CONSIDERED TO BE RELEVANT

Category	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
A	EP 0 495 549 A (DSM N.V.) 22 July 1992 See page 2, line 40 - line 49; claim 14 -----	1-22

INTERNATIONAL SEARCH REPORT

Information on patent family members

Internal Application No
PCT/US 97/06047

Patent document cited in search report	Publication date	Patent family member(s)	Publication date
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EP 0495549 A	22-07-92	NL 9100086 A EP 0495550 A JP 5032767 A JP 4307231 A US 5430073 A US 5362760 A	17-08-92 22-07-92 09-02-93 29-10-92 04-07-95 08-11-94

Docket # MUH-12807

Applic. # _____

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